TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM737461

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
RAJE Technology Group, LLC		06/02/2022	Limited Liability Company: FLORIDA
Plasma-Therm, LLC		06/02/2022	Limited Liability Company: FLORIDA
Rev-Tech Manufacturing Solutions, LLC		06/02/2022	Limited Liability Company: FLORIDA
Hine Automation, LLC		06/02/2022	Limited Liability Company: DELAWARE
Drytek, LLC		06/02/2022	Limited Liability Company: DELAWARE
Plasma-Therm NES, LLC		06/02/2022	Limited Liability Company: FLORIDA
Logix Technology Holdings, LLC		06/02/2022	Limited Liability Company: DELAWARE
Plasma Therm IC-DISC, Inc.		06/02/2022	Corporation: DELAWARE

RECEIVING PARTY DATA

Name:	Valley National Bank
Street Address:	1840 4th Street North
City:	St. Petersburg
State/Country:	FLORIDA
Postal Code:	33704
Entity Type:	National Banking Association: UNITED STATES

CH $340.00 3730528

PROPERTY NUMBERS Total: 13

Property Type	Number	Word Mark
Registration Number:	3730528	790+
Registration Number:	4136245	CORTEX
Registration Number:	3902954	ENDPOINTWORKS
Registration Number:	3383876	MASK ETCHER
Registration Number:	3687253	PLASMA-THERM
Registration Number:	3840760	PTI
Registration Number:	2893123	SHUTTLELINE
Registration Number:	1625640	SHUTTLELOCK

Property Type	Number	Word Mark
Registration Number:	4818288	SINGULATOR
Registration Number:	2893124	VERSALINE
Registration Number:	2001901	VERSALOCK
Registration Number:	3841335	VERSAWORKS
Registration Number:	4210502	DRYTEK

CORRESPONDENCE DATA

Fax Number: 8132212900

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 8132213900
Email: christina.allen@hwhlaw.com
Correspondent Name: Stephen E. Kelly
Address Line 1: 101 E. Kennedy Blvd., Suite 3700
Address Line 2: Suite 3700
Address Line 4: Tampa, FLORIDA 33602

NAME OF SUBMITTER:	Stephen E. Kelly
SIGNATURE:	/s/ Stephen E. Kelly
DATE SIGNED:	06/28/2022

Total Attachments: 15
source=Intellectual Property Security Agreement [Executed]#page1.tif
source=Intellectual Property Security Agreement [Executed]#page2.tif
source=Intellectual Property Security Agreement [Executed]#page3.tif
source=Intellectual Property Security Agreement [Executed]#page4.tif
source=Intellectual Property Security Agreement [Executed]#page5.tif
source=Intellectual Property Security Agreement [Executed]#page6.tif
source=Intellectual Property Security Agreement [Executed]#page7.tif
source=Intellectual Property Security Agreement [Executed]#page8.tif
source=Intellectual Property Security Agreement [Executed]#page9.tif
source=Intellectual Property Security Agreement [Executed]#page10.tif
source=Intellectual Property Security Agreement [Executed]#page11.tif
source=Intellectual Property Security Agreement [Executed]#page12.tif
source=Intellectual Property Security Agreement [Executed]#page13.tif
source=Intellectual Property Security Agreement [Executed]#page14.tif
source=Intellectual Property Security Agreement [Executed]#page15.tif

INTELLECTUAL PROPERTY SECURITY AGREEMENT

This INTELLECTUAL PROPERTY SECURITY AGREEMENT, dated as of June 2, 2022 (as amended, supplemented or otherwise modified from time to time, the Agreement"), is made by RAJE Technology Group, LLC, a Florida limited liability company, Plasma-Therm, LLC, a Florida limited liability company, Rev-Tech Manufacturing Solutions, LLC, a Florida limited liability company, Hine Automation, LLC, a Delaware limited liability company, Drytek, LLC, a Delaware limited liability company, Plasma-Therm NES, LLC, a Florida limited liability company, Logix Technology Holdings, LLC, a Delaware limited liability company, and Plasma Therm IC-DISC, Inc., a Delaware corporation (each sometimes hereafter referred to as a "Grantor" and collectively, the "Grantors") in favor of Valley National Bank, a national banking association (the "Lender").

RECITALS

The Grantors have entered into the Credit Agreement, dated the date hereof (the "Credit Agreement"), by and among the Grantors and the Lender. Pursuant to the Credit Agreement, the Grantors have entered into the Pledge and Security Agreement, dated the date hereof (as amended, restated, supplemented or otherwise modified from time to time, the "Security Agreement"), by and among the Grantors and the Lender, to secure the prompt payment and performance of any and all obligations of the Grantors. Capitalized terms used and not defined herein have the meanings given such terms in the Credit Agreement.

Each Grantor pursuant to the terms and conditions of the Security Agreement has granted a security interest in the Collateral (as defined in the Security Agreement) of such Grantor, including, but not limited to, all Intellectual Property (as defined in the Security Agreement) for the benefit of the Lender, and has agreed as a condition thereof to execute this Agreement for recording with the United States Patent and Trademark Office, the United States Copyright Office, and any other applicable Governmental Authority.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the Grantors agree as follows:

SECTION 1. Grant of Security. Each Grantor hereby grants to the Lender a security interest in and to all of such Grantor's right, title and interest in and to the following Intellectual Property, whether now existing or hereafter arising, as collateral security for the prompt and complete payment and performance when due (whether at the stated maturity, by acceleration or otherwise) of the Obligations:

(a) all Patents (as defined in the Security Agreement), including, without limitation, each issued patent and patent application identified in Schedule 1 (as amended, restated, supplemented or otherwise modified from time to time), and all other rights of any kind whatsoever of such Grantor accruing thereunder or pertaining thereto (collectively, the "Pledged Patents");

(b) all Trademarks (as defined in the Security Agreement), including, without limitation, each registration and application identified in Schedule 2 (as amended, restated, supplemented or otherwise modified from time to time), and all other rights of any kind whatsoever of such Grantor accruing thereunder or pertaining thereto, together in each case with the goodwill of the business

connected with the use of, and symbolized by, each of the above (collectively, the "Pledged Trademarks");

(c) all Copyrights (as defined in the Security Agreement), including, without limitation, each registration and application identified in Schedule 3 (as amended, restated, supplemented or otherwise modified from time to time), and all other rights of any kind whatsoever of such Grantor accruing thereunder or pertaining thereto (collectively, "Pledged Copyrights"); and

(d) any and all proceeds of the foregoing.

SECTION 2. Recordation. Each Grantor authorizes and requests that the Register of Copyrights, the Commissioner of Patents and Trademarks and any other applicable government officer to record and file this Agreement.

SECTION 3. Execution in Counterparts. This Agreement may be executed in any number of counterparts as necessary or convenient and by the different parties on separate counterparts (including by electronic transmission), each of which when so executed shall be deemed to be an original and all of which taken together shall constitute one and the same agreement. Delivery of an executed counterpart of this Amendment (or of any agreement or document required by this Agreement) by telecopy or other electronic imaging means (including, but not limited to, .PDF via email) shall be as effective, valid and legally binding as delivery of a manually executed counterpart of this Agreement; provided, however, that the telecopy or other electronic image shall be promptly followed by an original if required by the Lender.

SECTION 4. Governing Law. This Agreement shall be governed by, and construed and interpreted in accordance with the laws of the State of Florida.

SECTION 5. Conflict Provision. This Agreement has been entered into in conjunction with the provisions of the Security Agreement. The rights and remedies of each party hereto with respect to the security interest granted herein are without prejudice to, and are in addition to those set forth in the Security Agreement, all terms and provisions of which are incorporated herein by reference. In the event that any provisions of this Agreement are in conflict with any Security Agreement, the provisions of such Security Agreement shall govern.

[Signature page follows]

IN WITNESS WHEREOF, each of the undersigned has caused this Agreement to be duly executed and delivered as of the date first above written.

GRANTORS:

RAJE TECHNOLOGY GROUP, LLC,
a Florida limited liability company

By: _____
Abdul Lateef, Chief Executive Officer

PLASMA-THERM, LLC,
a Florida limited liability company

By: _____
Abdul Lateef, Chief Executive Officer

REV-TECH MANUFACTURING SOLUTIONS, LLC, a Florida limited liability company

By: _____
Abdul Lateef, Chief Executive Officer

HINE AUTOMATION, LLC,
a Delaware limited liability company

By: _____
Abdul Lateef, President

DRYTEK, LLC,
a Delaware limited liability company

By: _____
Abdul Lateef, Chief Executive Officer

(Signature Page to Intellectual Property Security Agreement)

PLASMA-THERM NES, LLC,
a Florida limited liability company

By: _____
Abdul Lateef, Chief Executive Officer

LOGIX TECHNOLOGY HOLDINGS, LLC,
a Delaware limited liability company

By: _____
Abdul Lateef, Chief Executive Officer

PLASMA-THERM IC-DISC, INC.,
a Delaware corporation

By: _____
Abdul Lateef, Chief Executive Officer

(Signature Page to Intellectual Property Security Agreement)

Schedule 1

Pledged Patents

Registered Owner: Plasma-Therm, LLC

Inventor	Title	Priority Filing Date Priority App No.	Utility File Date Utility App No.	Pub. Date Pub. No.	Issue Date Issue No.
Plumhoff Ryan Nolan Johnson Westerman	Temperature Control Method for Photolithographic Substrate	06/05/2006 60/811,139	5/31/2007 11/756,074	6/26/2008 2008-0149597	01/11/2011 7,867,403
Lai Mackenzie Johnson	A Method and Apparatus for Plasma Etching of Positively Sloped Structures	08/09/2006 60/836,483	8/6/2007 11/834127	3/13/2008 2008-0061029	11/09/2010 7,829,465
Johnson Westerman	Method for Etching Vias	04/09/2002 60/371,056	04/04/2003 10/407,831	11/20/2003 2003-0216034	1/25/2005 6,846,747
Plumhoff Srinivasan Westerman Johnson	Method to Minimize CD Etch Bias	08/11/2006 60/837,593	8/6/2007 11/834299	2/14/2008 2008-0035606	05/29/2012 8,187,483
Reynolds	Conductive Seal Ring Electrostatic Chuck	1/20/2009 61/145,871	1/19/2010 12/689,784	02/03/2011 2011-0026187	03/20/2012 8,139,340
Westerman Johnson Lai	Notch-free Etching of High Aspect SOI structures using Alternating Deposition and Etching and Pulsed ICP	07/24/2002 60/398,347	06/19/2003 10/601,076	3/25/2004 2004-0055995	6/14/2005 6,905,626
Westerman Johnson Lai	Sidewall smoothing in high aspect ratio/deep etching using a discrete gas switching method	08/16/2002 60/403,891	08/12/2003 10/640,469	5/13/2004 2004-0092118	8/2/2005 6,924,235

CW Johnson DJ Johnson Pays-Volard Martinez Westerman Grivna	Method and Apparatus for Plasma Dicing a Semi-conductor Wafer (2 step process)	03/14/2011 61/452,450	03/05/2012 13/412,119	03/14/2013 2013-0065378	08/12/2014 8,802,545
CW Johnson DJ Johnson Pays-Volard Martinez Westerman Grivna	DIV of (PT-182) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer (Dicing on Tape)	03/14/2011 61/452,450	4/17/2012 13/448,769	09/20/2012 2012-0238073	07/15/2014 8,778,806
Falvo Martinez Pays-Volard Gauldin Westerman	Method for Dicing a Substrate with Back Metal (Water Jet)	09/28/2012 61/707,464	09/23/2013 14/034,164	04/03/2014 2014-0094018	06/14/2016 9,368,404
Falvo Martinez Pays-Volard Gauldin Westerman	DIV of (PT-194) Method for Dicing a Substrate with Back Metal (Water Jet)	09/28/2012 61/707,464	05/06/2016 15/148,707	09/01/2016 2016-0254189	12/03/2019 10,497,621
CW Johnson DJ Johnson Pays-Volard Martinez Westerman Grivna	DIV of (PT-182) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - Cover Ring	03/14/2011 61/452,450	02/11/2013 13/764,110	09/05/2013 2013-0230972	08/05/2014 8,796,154
CW Johnson DJ Johnson Martinez Pays-Volard Rich Gauldin Westerman Grivna	DIV of (PT-182) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - Lift Mechanism	03/14/2011 61/452,450	02/11/2013 13/764,142	09/05/2013 2013-0230968	07/22/2014 8,785,332
CW Johnson DJ Johnson Martinez Pays-Volard Rich Gauldin Westerman Grivna	DIV of (PT-196) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - Lift Mechanism	03/14/2011 61/452,450	09/14/2018 16/132,040	01/10/2019 2019-0013243	07/07/2020 10,707,060

Martinez Pays-Volard CW Johnson DJ Johnson Westerman Grivna	DIV of (PT-182) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - ICP Screen	03/14/2011 61/452,450	02/11/2013 13/764,160	09/05/2013 2013-0230969	03/17/2015 8,980,764
Martinez Pays-Volard CW Johnson DJ Johnson Westerman Grivna	DIV of (PT-182) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - ESC	03/14/2011 61/452,450	02/11/2013 13/764,177	09/05/2013 2013-0230970	12/01/2015 9,202,720
Martinez Pays-Volard CW Johnson DJ Johnson Westerman Grivna	DIV of (PT-198) Apparatus for Plasma Dicing a Semi-conductor Wafer - ESC	03/14/2011 61/452,450	09/01/2015 14/842,365	12/24/2015 2015-0371878	05/21/2019 10,297,427
Martinez Pays-Volard CW Johnson DJ Johnson Westerman Grivna	DIV of (PT-198) Apparatus for Plasma Dicing a Semi-conductor Wafer - (TDM & Cleaning Step)	03/14/2011 61/452,450	12/18/2015 14/974,840	04/21/2016 2016-0111332	02/07/2017 9,564,366
Gauldin CW Johnson DJ Johnson Martinez Pays-Volard Westerman Grivna	CIP of (PT-182) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - Tape Under Tension & Multiple Wafer	03/14/2011 61/452,450	02/14/2013 13/767,459	09/05/2013 2013-0230973	02/03/2015 8,946,058
Gauldin CW Johnson DJ Johnson Martinez Pays-Volard Westerman Grivna	Reissue of (PT-199) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - Tape Under Tension & Multiple Wafer	03/14/2011 61/452,450	09/15/2015 14/854,127		03/14/2017 RE46339
Martinez Pays-Volard CW Johnson DJ Johnson Westerman Grivna	CIP of (PT-182) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - large area ESC Details with cover ring	03/14/2011 61/452,450	03/06/2013 13/787,032	09/05/2013 2013-0230974	06/30/2015 9,070,760

Martinez Pays-Volard CW Johnson DJ Johnson Westerman Grivna	DIV of (PT-201) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - lift mechanism engaging a bottom surface of the work piece	03/14/2011 61/452,450	05/26/2015 14/721,443	09/10/2015 2015-0255347	11/15/2016 9,496,177
Pays-Volard Martinez CW Johnson DJ Johnson Westerman Grivna	DIV of (PT-201) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - ICP screen details	03/14/2011 61/452,450	03/06/2013 13/787,153	08/21/2014 2014-0235034	08/11/2015 9,105,705
Pays-Volard Martinez CW Johnson DJ Johnson Westerman Grivna	DIV of (PT-205) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - 13.56MHz SOI & mechanical partition	03/14/2011 61/452,450	06/03/2015 14/729,610	09/24/2015 2015-0270121	02/25/2020 10,573,557
Geerpuram Pays-Volard Martinez CW Johnson DJ Johnson Westerman	CIP of (PT-182) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - Perforated Cover Ring, Multi-Wafer Cover Ring & PCM Fills	03/14/2011 61/452,450	03/14/2013 13/829,324	09/05/2013 2013-0230971	04/08/2014 8,691,702
Lazerand Pays-Volard Martinez CW Johnson Westerman Grivna	CIP of (PT-182) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - Dicing Assist Feature	03/14/2011 61/452,450	08/29/2013 14/014,040	12/26/2013 2013-0344683	05/17/2016 9,343,365
Geerpuram Pays-Volard Martinez CW Johnson DJ Johnson Westerman	DIV of (PT-206) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - Perforated Cover Ring, Multi-Wafer Cover Ring & PCM Fills	03/14/2011 61/452,450	02/10/2014 14/176,747	06/05/2014 2014-0154869	12/01/2015 9,202,721

Gauldin Geerpuram Mackenzie Lazerand Pays-Volard Martinez Westerman Grivna Doub	CIP of (PT-182) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - intermediate ring with cover ring	03/14/2011 61/452,450	03/07/2014 14/201,409	08/28/2014 2014-0242780	07/14/2015 9,082,839
Gauldin Geerpuram Mackenzie Lazerand Pays-Volard Martinez Westerman Grivna Doub	DIV of (PT-217) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - intermediate ring without cover ring	03/14/2011 61/452,450	06/02/2015 14/728,517	09/24/2015 2015-0270154	12/01/2015 9,202,737
Westerman Johnson	End Point Detection in Time Division Multiplexed Etch Processes	02/14/2003 60/447,594	02/02/2004 10/770,839	9/9/2004 2004-0175913	1/3/2006 6,982,175
Westerman Johnson Lai	A Method and Apparatus for Process Control in Time Division Multiplexed (TDM) Etch Processes	04/07/2003 60/460,932	03/31/2004 10/815,965	11/15/2004 2004-0235307	10/3/2006 7,115,520
Baujon Guidotti Pilloux Rabinzohn Richard Segers Girault	DIV of (PT-241) Device for Treating an Object with Plasma	07/20/2012 FR1257037	01/13/2018 15/870,890	06/07/2018 2018-0158651	07/27/2021 11,075,057
Chiang Westerman	Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - GaAs	11/30/2016 62/428,078	11/28/2017 15/824,166	05/31/2018 2018-0151435	04/23/2019 10,269,641
Chiang Westerman	DIV filing of (PT243) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - GaAs	11/30/2016 62/428,078	02/19/2019 16/279,560	06/20/2019 2019-0189513	10/27/2020 10,818,552

Hegde Lee	Powered Anode for Ion Source for DLC and Reactive Processes	06/10/2016 62/348,751	07/10/2016 15/206,300	n/a	01/09/2018 9,865,436
Hegde Lee Goglia	Wafer Stage for Symmetric Wafer Processing	04/25/2014 61/984,600	04/27/2015 14/697,441	10/29/2015 2015-0307986	01/09/2018 9,863,036
Hegde	Grid Assemblies for Use in Ion Beam Etching Systems and Methods of Utilizing the Grid Assemblies	n/a	10/02/2008 12/244,681	n/a	04/22/2014 8,703,001
Martinez Pays-Volard CW Johnson DJ Johnson Westerman Grivna	DIV of (PT-201.1) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - large area ESC Details without cover ring	03/14/2011 61/452,450	10/06/2016 15/287,412	01/26/2017 2017-0025311	03/06/2018 9,911,654
Martinez Pays-Volard CW Johnson DJ Johnson Westerman Grivna	DIV of (PT-263) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - ICP screen adjustment	03/14/2011 61/452,450	03/02/2018 15/910,561	07/05/2018 2018-0190542	08/11/2020 10,741,447
Martinez Pays-Volard CW Johnson DJ Johnson Westerman Grivna	DIV of (PT-201.2) Method and Apparatus for Plasma Dicing a Semi-conductor Wafer - Frame & Cover Ring (Tape & Frame Exposed)	03/14/2011 61/452,450	10/06/2016 15/287,501	02/02/2017 2017-0033008	07/18/2017 9,711,406
Constantine Plumhoff Johnson Westerman	Etching of Chromium Layers on Photomasks Utilizing High Density Plasma and Low Frequency RF Bias	05/05/2003 60/468,118	05/03/2004 10/839,809	12/23/2004 2004-0259367	3/7/2006 7,008,877
Hegde Lee	Scanning Ion Beam Etch	05/03/2018 62/666,324	04/30/2019 16/398,487	11/07/2019 2019-0341221	01/18/2022 11,227,741

Notarianni Lea Westerman	Method for Dicing Die Attach Film - VHF	06/04/18 62/680,145	03/19/2019 16/358,017	03/12/2020 2020-0083084	03/09/2021 10,943,825
Vitiello Delcarri Piallat	METHOD FOR REMOVING A METAL DEPOSIT PLACED ON A SURFACE IN A CHAMBER	07/24/2014 FR20140057137	01/23/2017 15/328,413	07/20/2017 2017-0204522	04/02/2019 10,246,781
Vitiello Piallat	METHOD FOR PRODUCING AN INTERCONNECTION COMPRISING A VIA EXTENDING THROUGH A SUBSTRATE	01/19/2016 FR1650408	07/16/2018 16/070,506	07/01/21 2021-0202314	09/07/2021 11,114,340
Vitiello Piallat	METHOD FOR REMOVING A METAL DEPOSIT ARRANGED ON A SURFACE IN A CHAMBER	01/19/2016 FR1650407	07/16/2018 16/070,491	01/31/2019 2019-0032199	09/08/2020 10,767,257
Johnson Westerman	Envelope Follower End Point Detection in Time Division Multiplexed Processes	05/09/2003 60/469,333	05/06/2004 10/841,818	12/2/2004 2004-0238489	09/05/2006 7,101,805
Nal Borean	TREATMENT CHAMBER FOR A CHEMICAL VAPOR DEPOSITION (CVD) REACTOR AND THERMALIZATION PROCESS CARRIED OUT IN THIS CHAMBER	01/16/2017 FR1750316	06/26/2019 16/473,860	10/24/2019 2019-0323123	12/07/2021 11,193,207
Vitiello Piallat	METHOD FOR DEPOSITING AN INSULATING MATERIAL INTO A VIA	08/29/2017 FR57951	01/22/2020 16/633,086	07/23/2020 2020-0234951	11/30/2021 11,189,486

Kenney	Perimeter seal for backside cooling	07/30/2001 60/308,734	06/06/2002 10/163,567	1/30/2003 2003-0021077	8/3/2004 6,771,482
Westerman Johnson Lai	A Method and Apparatus for Reducing Aspect Ratio Dependent Etching in TDM Etch Processes	06/29/2004 60/584,470	06/23/2005 11/159,415	12/29/2005 2005-0287815	06/14/2011 7,959,819
Westerman Johnson	Method and Apparatus to Improve Plasma Etch Uniformity	10/4/2004 60/615,860	09/16/2005 11/229,319	4/6/2006 2006-0070703	05/11/2010 7,713,432
Plumhoff	Method for Process Change Detection	6/16/2005 60/690,941	05/26/2006 11/441,811	12/21/2006 2006-0287753	12/1/2009 7,625,824
Westerman Johnson Lai Teixeira	CIP of (PT-24) A Method and Apparatus for Process Control in Time Division Multiplexed (TDM) Etch Processes	04/07/2003 60/460,932	06/20/2005 11/155,904	12/1/2005 2005-0263485	6/3/2008 7,381,650
Johnson	Optical Emission Interferometry for PECVD using a Gas Injection Hole	8/18/2005 60/709,469	08/10/2006 11/502,585	2/22/2007 2007-0039548	11/16/2010 7,833,381
Plumhoff	Improved Method for Etching Photolithographic Substrates	12/16/2005 60/751,349	12/4/2006 11/634,377	6/21/2007 2007-0138136	07/06/2010 7,749,400
BOREAN DELCARRI	DEVICE AND PROCESS FOR CHEMICAL VAPOR PHASE TREATMENT	04/28/2008 FR20080002375	01/24/2011 12/990,143	06/16/2011 US2011143551	03/03/2015 US8967081
NAL BOREAN VITIELLO	CHEMICAL VAPOR DEPOSITION DEVICE	02/21/2013 FR20130051526	08/20/2015 14/769,414	01/07/2016 US2016-0002788	10/03/2017 9,777,374

Westerman Constantine	Embedded attenuated phase shift mask and method of making embedded attenuated phase shift mask	12/1/2000 60/250,351	11/30/2001 09/996,748	06/06/2002 2002-068229	4/8/2003 6,544,696

Schedule 2

Pledged Trademarks

Registered Owner: Plasma-Therm, LLC

Registered Trademark	Registration Number
"790+"	3,730,528
"Cortex"	4,136,245
"Endpointworks"	3,902,954
"Mask Etcher"	3,383,876
"Plasma-Therm"	3,687,253
PTI Logo: 	3,840,760
"Shuttleline"	2,893,123
"Shuttlelock"	1,625,640
"Singulator"	4,818,288
"Versaline"	2,893,124
"Versalock"	2,001,901
"Versaworks"	3,841,335

Registered Owner: Drytek, LLC

Registered Trademark	Registration Number
"Drytek""	4,210,502

Schedule 3

Pledged Copyrights

None.